



Material Content Data Sheet



Sales Product Name		BSS169 H6327		Issued		24. January 2018		
MA#		MA001231770						
Package		PG-SOT23-3-5		Weight*		9.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.04		393	
	noble metal	gold	7440-57-5	0.014	0.15		1524	
	inorganic material	silicon	7440-21-3	0.161	1.73	1.92	17270	19187
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		967	
	inorganic material	silicon	7440-21-3	0.001	0.01		65	
	non noble metal	titanium	7440-32-6	0.003	0.03		322	
	non noble metal	copper	7440-50-8	3.000	32.11	32.25	321077	322431
wire	non noble metal	copper	7440-50-8	0.007	0.08	0.08	788	788
encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6112	
	plastics	epoxy resin	-	1.228	13.14		131396	
	inorganic material	silicondioxide	60676-86-0	4.426	47.36	61.11	473637	611145
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	16013	16013
plating	noble metal	silver	7440-22-4	0.284	3.04	3.04	30436	30436
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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